

SAW DEVICES



HUAFENG
CRYSTAL

SAW RESONATORS

- Frequency can be obtained directly and no amplification circuit is required
- Free from spurious response
- High frequency and wide frequency range
- Excellent frequency stability vs temperature variation

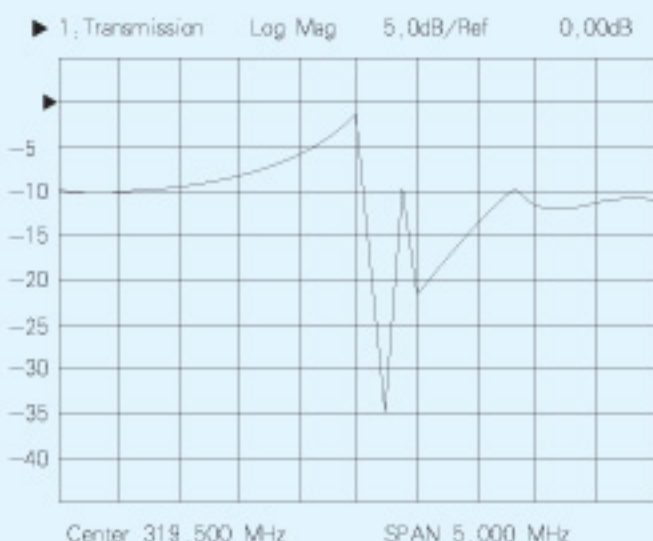


ELECTRICAL SPECIFICATIONS

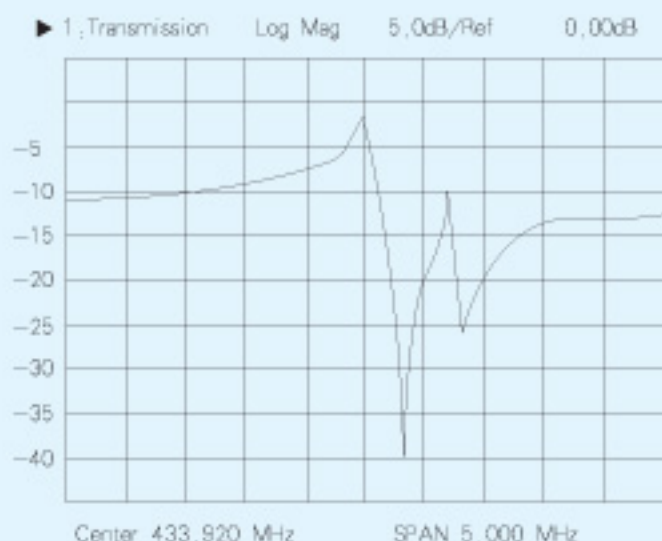
Maximum Rating	DC Voltage V_{DC} AC Voltage V_{PP} Operating Temperature Storage Temperature RF Power Dissipation	10V 10V(50Hz / 60Hz) -40to +85°C -40to +85°C 0dBm
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Frequency (MHz)	Deviation (kHz)	Insertion Loss (dB Max)	Package	Substrate Materials	Freq.Temp. Coefficient
315.00	±75	2.5	TO-39	ST-Q	0.032ppm/°C ²
318.00	±75	2.5	TO-39	ST-Q	0.032ppm/°C ²
319.50	±75	2.5	TO-39	ST-Q	0.032ppm/°C ²
418.00	±75	2.5	TO-39	ST-Q	0.032ppm/°C ²
433.92	±75	2.5	TO-39	ST-Q	0.032ppm/°C ²

CHARACTERISTIC DIAGRAM

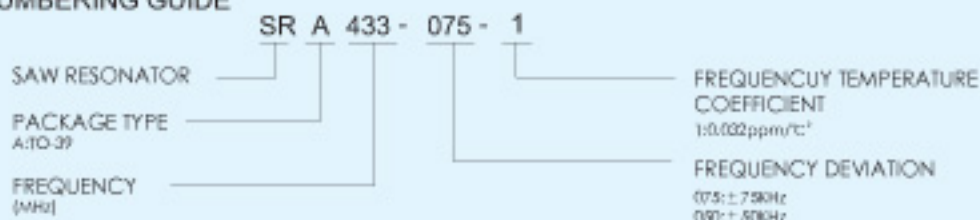


SR319

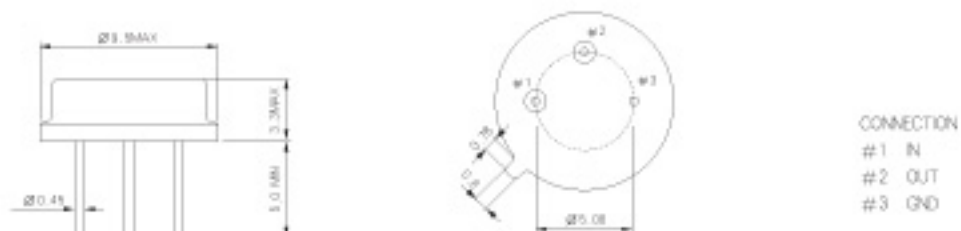


SR433

■ PART NUMBERING GUIDE



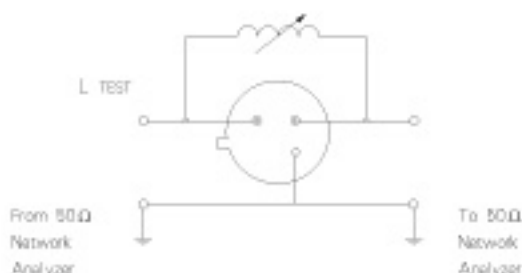
■ MECHANICAL DIMENSIONS



■ EQUIVALENT LC MODEL



■ TEST CIRCUIT



■ REMARKS

Static voltage	Static voltage between signal load & ground may cause deterioration & destruction of the component. Please avoid static voltage.
Ultrasonic cleaning	Ultrasonic vibration may cause deterioration & destruction of the component. Please avoid ultrasonic cleaning.
Soldering	Only leads of component may be soldered. Please avoid soldering another part of component.

■ ENVIRONMENTAL / MECHANICAL SPECIFICATIONS

PARAMETER	SPECIFICATIONS
Shock	The components shall remain within the electrical specifications after 1000 shocks, acceleration 392 m/s ² , duration 6 msec.
Vibration	The components shall remain within the electrical specifications after loaded vibration at 20 Hz, amplitude 1.5 mm, for 2 hours.
Solder-heat Resistance	The components shall remain within the electrical specifications after dipped in the solder at 260°C for 10 ± 1 seconds, then kept at room temperature for 2 hours. (Terminal must be dipped leaving 1.5mm from the case).
Solderability	Solderability of terminal shall be kept at more than 80% after dipped in the solder flux at 230°C ± 5°C for 5 ± 1 seconds.